



## Keeping an Eye on Implant Materials

Dennis Brestovansky

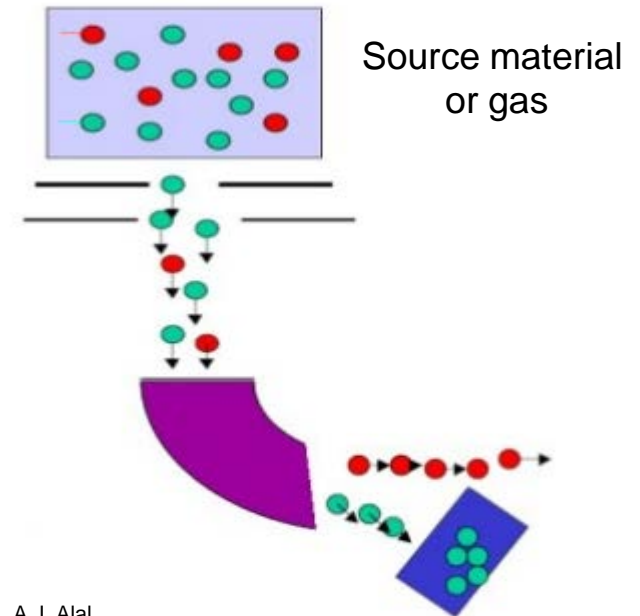
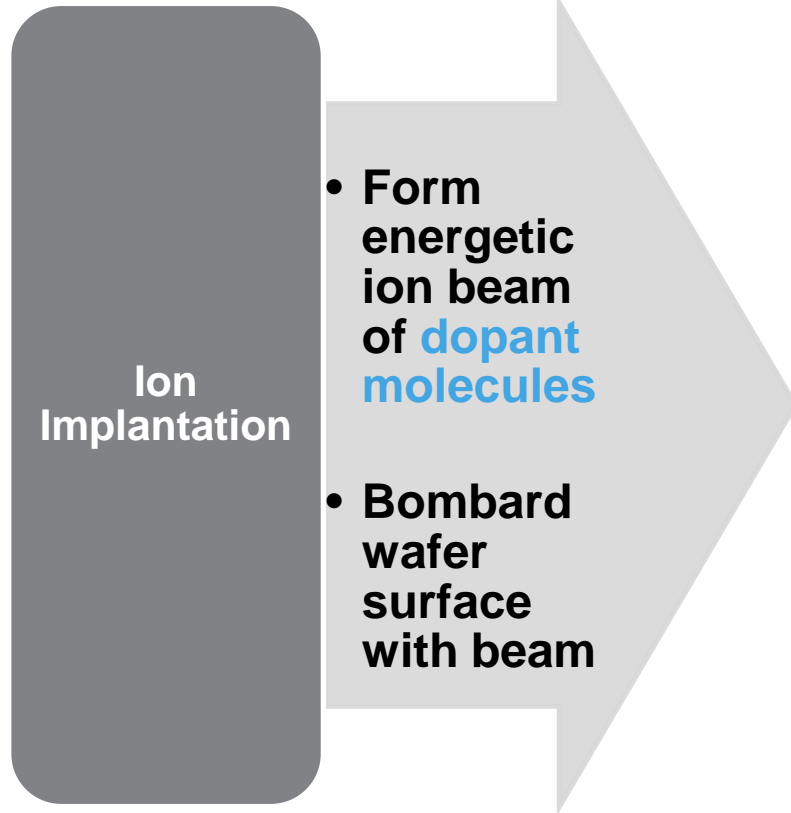
Technology Commercialization Director



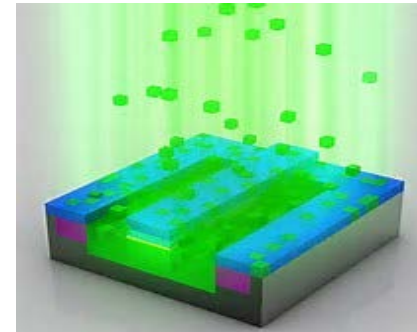
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- Some important characteristics of Ion Implantation
- Properties of Source Materials
- Materials Handling Considerations
- Materials Choice Tradeoffs
  - Handling / Packaging
  - Supply Chain Robustness
- Influence of Source Material Choice on Cost and Performance
  - Throughput
  - Maintenance
- Overview of Materials Landscape
- Emerging Materials

# Implant Process



A.J. Alal  
[www.slideshare.net/ajal4u/ion-implantation-37881199](http://www.slideshare.net/ajal4u/ion-implantation-37881199)



# Unique Materials Supply Situation



- Toxic / flammable / corrosive materials
- Stored inside tool – not remotely
- In vicinity of personnel
- Tool shutdown to change



# Common Materials and Hazards

	Arsine	Phosphine	Boron Trifluoride
Phase	Liquified Compressed Gas	Liquified Compressed Gas	Compressed Gas
Hazard	Highly flammable	Highly flammable	Highly corrosive
OSHA PEL	0.05 ppm	0.3 ppm	1 ppm

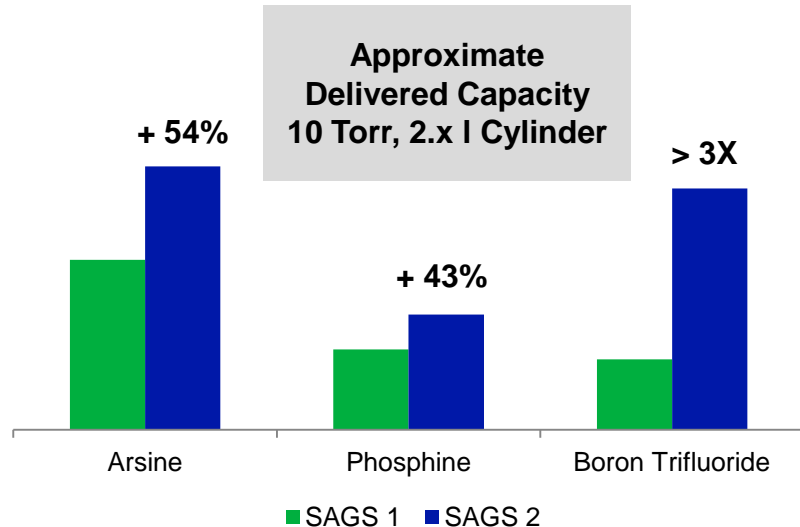
- Convenient gas phase at room temperature and pressure
- Careful handling required to protect personnel and equipment
- Implanter design considerations prohibit remote storage, e.g. sub-fab



SAGS-1 - Adsorbent



SAGS-2 - Mechanical

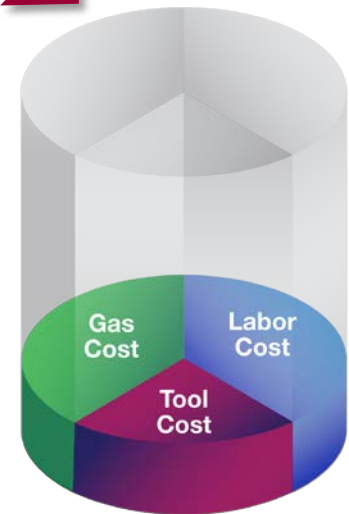
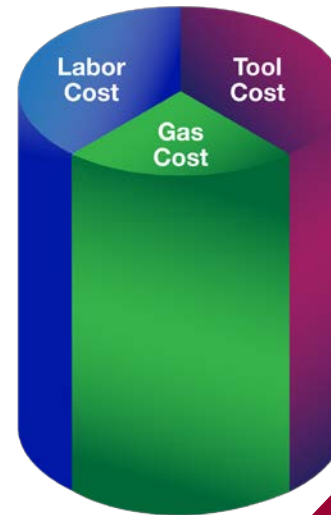


## Tradeoffs / Considerations

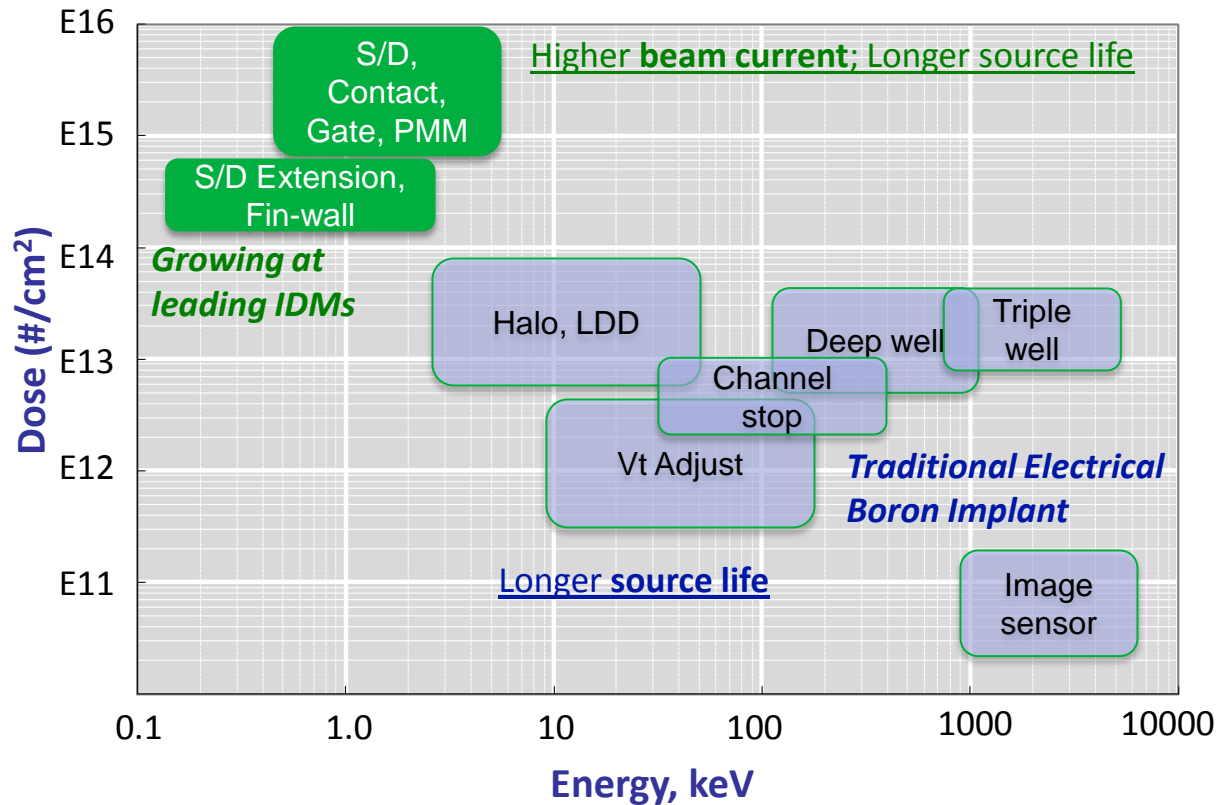
- Physics
  - Temperature
  - Air infiltration
  - Pressurization
- Capacity
  - Handling frequency
- Utilization
  - Cost
- Design
  - Absorptivity
  - Mixture capable

# Ion Implantation Cost Factors

- Source Material Costs
  - Price per unit
  - Utilization
- Labor Costs
  - Source material change frequency
  - Tool MTTR / MTBF
- Productivity
  - Throughput
    - Ion beam current
    - Species changeover speed
    - Tool availability
  - Yield
    - Particles
    - Glitch rate / beam uniformity



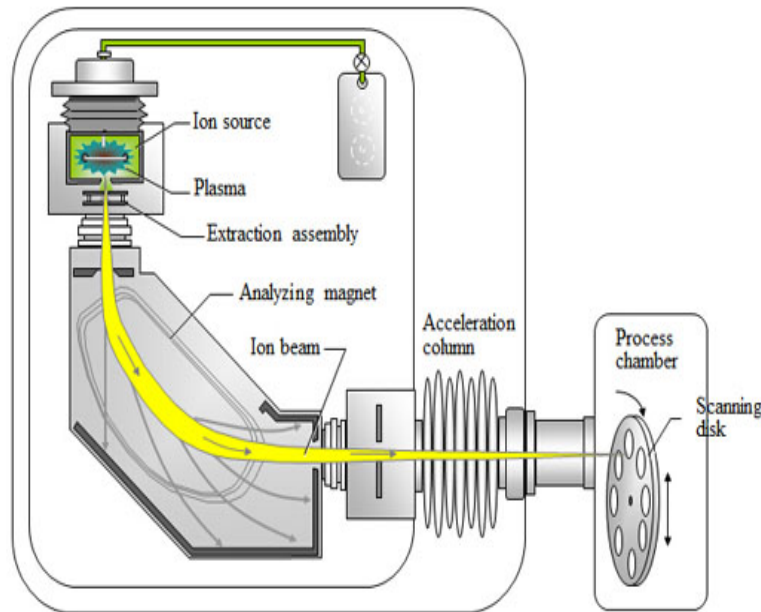
# Evolution of Implantation



- Remains an important process even with advancing nodes
- Electrical and materials modification applications
- Increasing demands on process, source materials and delivery
  - Example : Higher current = higher desired beam current
  - Example : Dedicated species operation = ion source life strain



# Cost Reduction Approaches



After : [www.samaterials.com](http://www.samaterials.com)

## How to ?

- Reduce preventive maintenance
- Increase throughput when fab is loaded – run as fast as possible
- Minimize defects

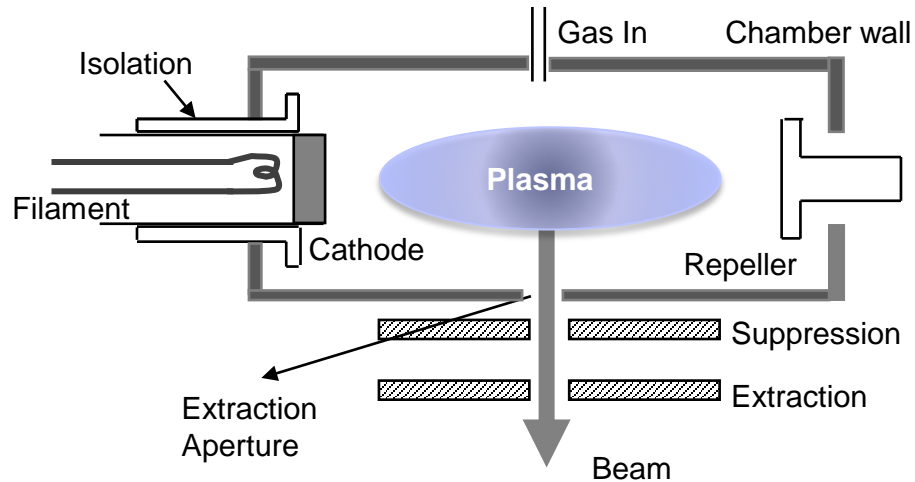
## Options:

- Increase number of tools
- Tool / Equipment modification
- Operating mode – species swap
- Choice of source molecule(s)

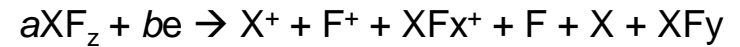
**Source molecule selection can be a “drop in” productivity enhancer**

# A Key Maintenance Issue

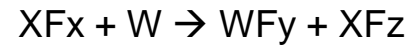
## IHC Source Schematic



### Initiation



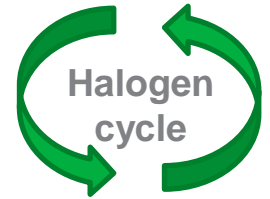
### Etching



### Deposition



X = e.g. B or Ge



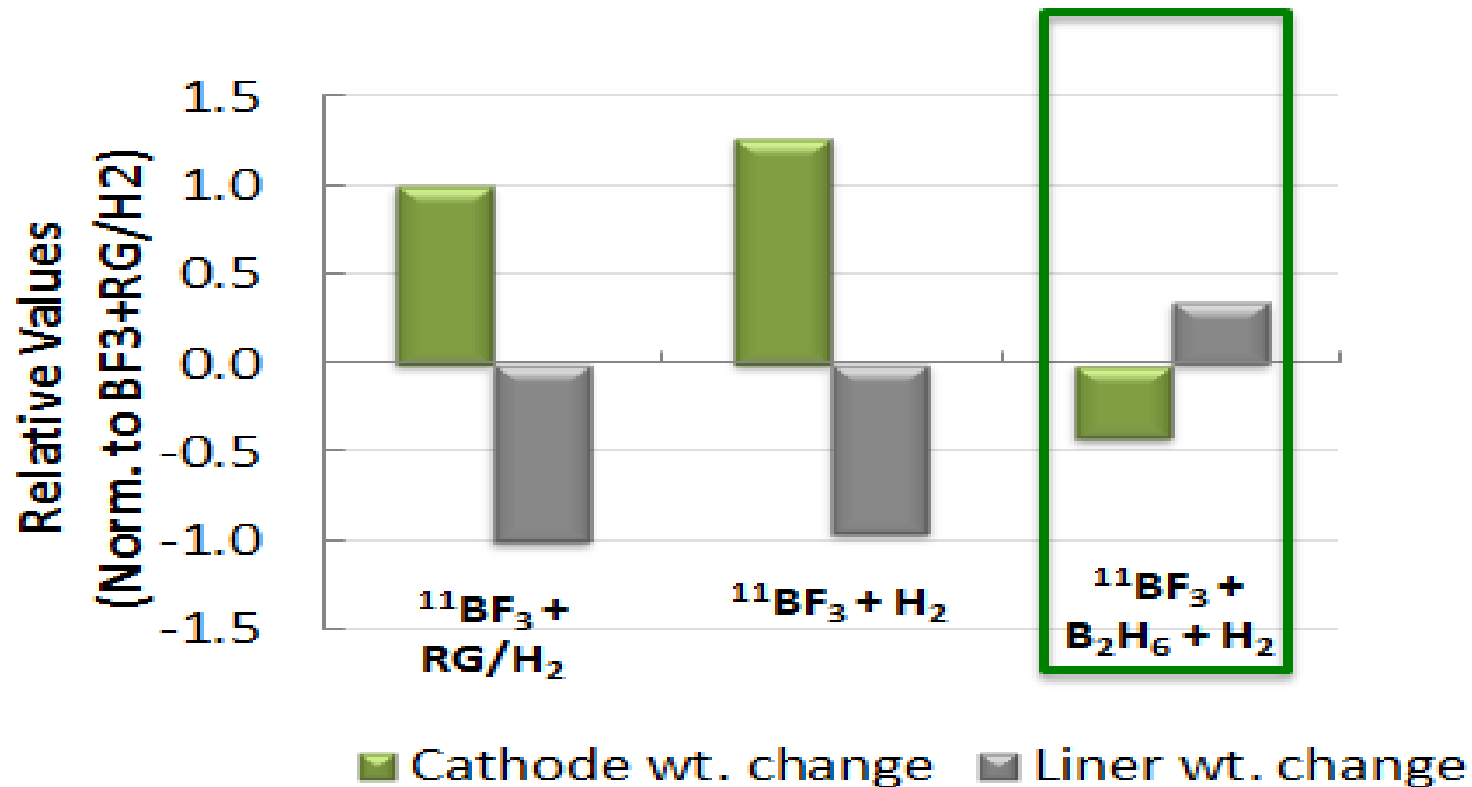
- “Halogen Cycle”
- Source materials can degrade implanter components
- Eventually, ion source chamber must be repaired / replaced leading to downtime and cost

**Want both long source life and beam current flexibility**

# Enhanced Productivity

## Changing chemistry to reduce ion source degradation

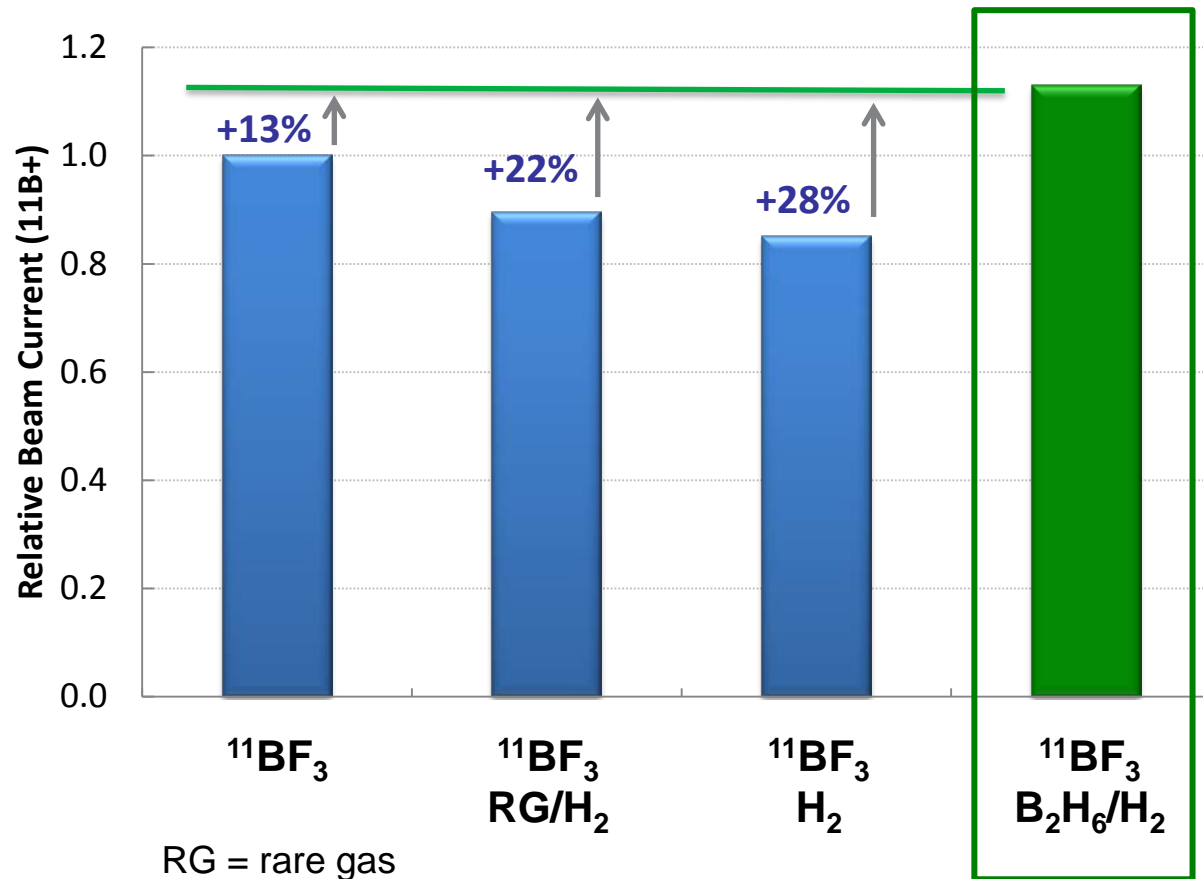
- + 70% ion source lifetime ..... > 230 hours



RG = rare gas

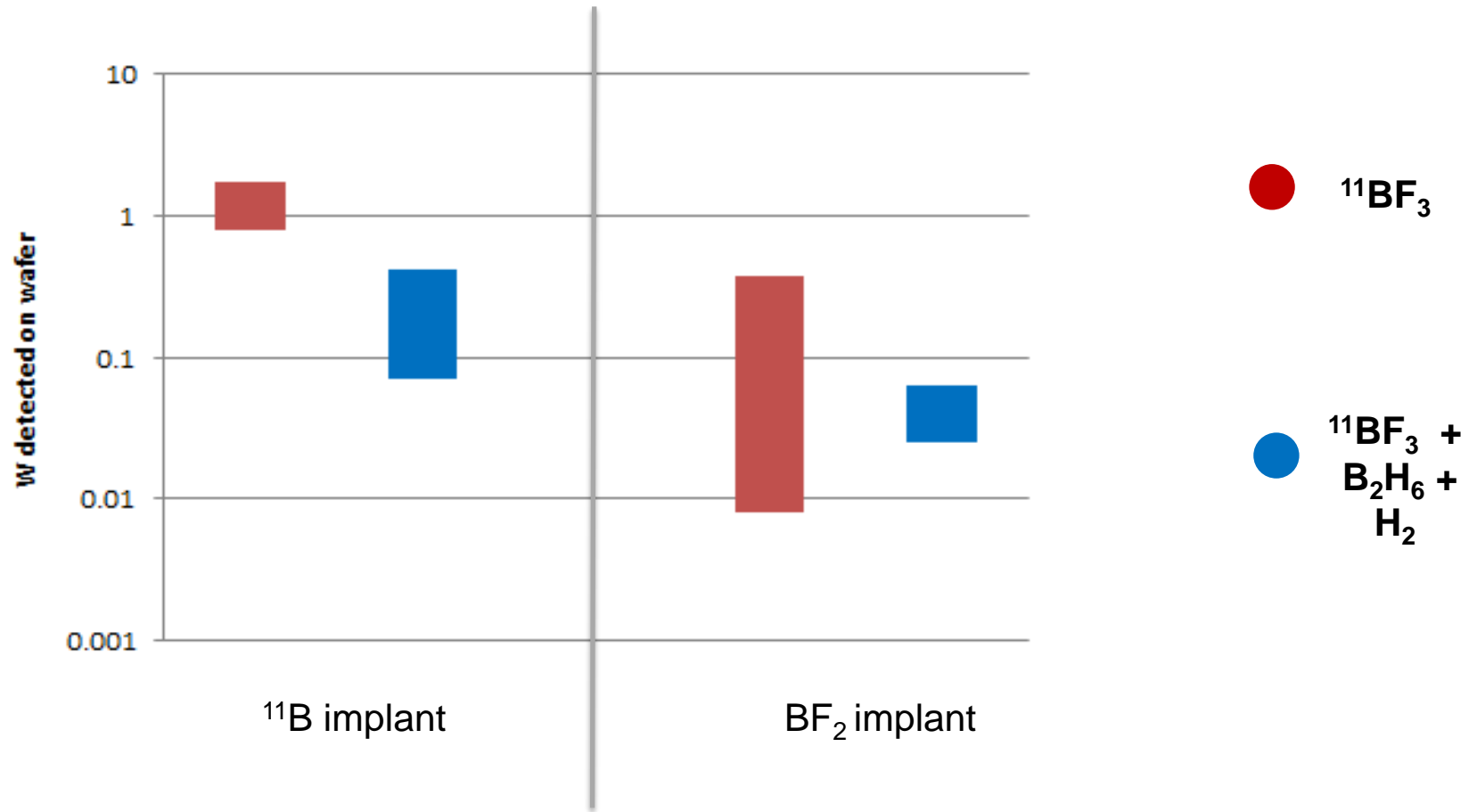
## Source Material Impact on Beam Current

- 22 to 28% better beam current while extending ion source lifetime



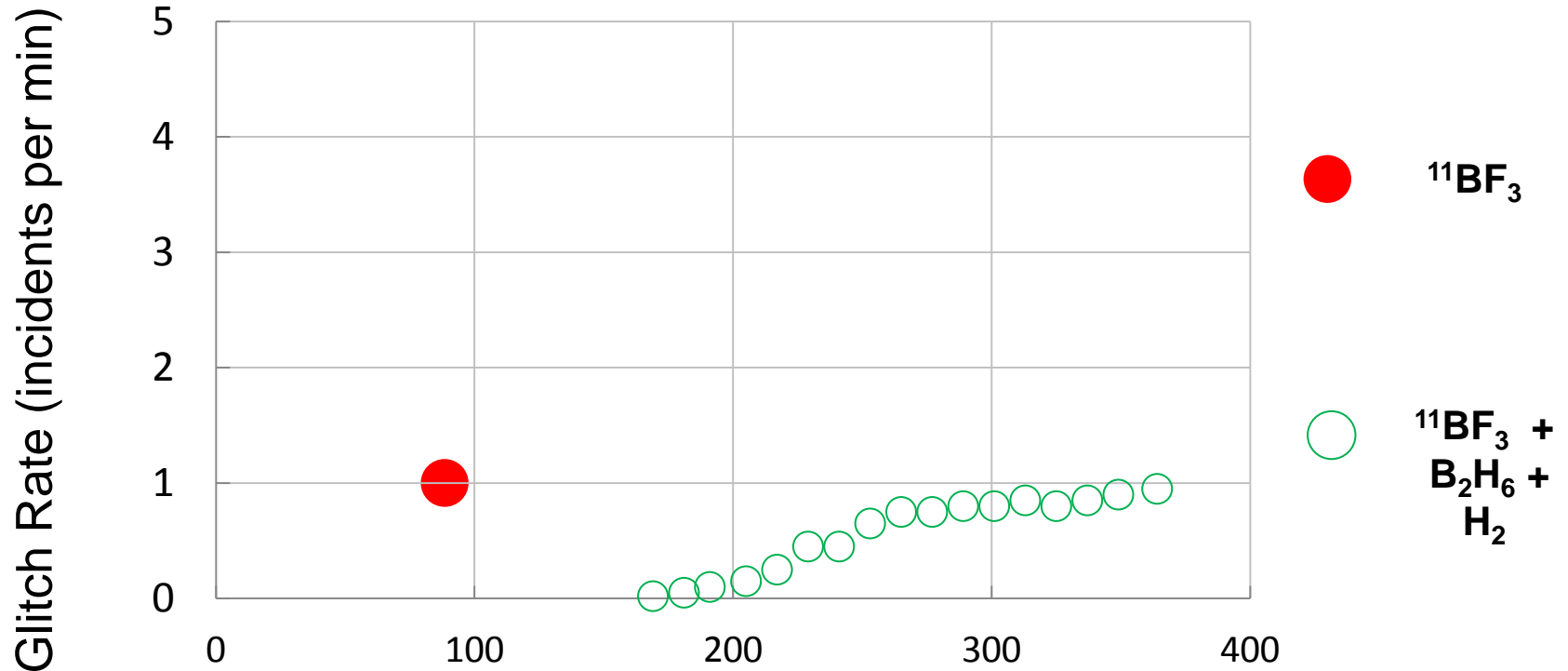
# Enhanced Yield - Contamination

Reduced levels of W on wafer from particles .....+20% yield



# Enhanced Yield – Dose Precision

Better beam stability through 370 hours at +20% beam current



# Options

Dopant	Baseline Material	Beam Current	Ion Source Lifetime	Mixed Mode Operation	Considerations
As	AsH <sub>3</sub>	-----	-----	-----	-----
P	PH <sub>3</sub>	-----	-----	PF <sub>3</sub>	PF <sub>3</sub> not as widely used in other processes
B	<sup>11</sup> BF <sub>3</sub>	<sup>11</sup> BF <sub>3</sub> / B <sub>2</sub> H <sub>6</sub> / H <sub>2</sub>	<ul style="list-style-type: none"> <li>• <sup>11</sup>BF<sub>3</sub> / H<sub>2</sub></li> <li>• <sup>11</sup>BF<sub>3</sub> / RG / H<sub>2</sub></li> <li>• <sup>11</sup>BF<sub>3</sub> / B<sub>2</sub>H<sub>6</sub> / H<sub>2</sub></li> </ul>	-----	Package design
Ge	GeF <sub>4</sub>	<ul style="list-style-type: none"> <li>• <sup>72</sup>GeF<sub>4</sub></li> <li>• GeF<sub>4</sub>/CH<sub>3</sub>F</li> </ul>	<ul style="list-style-type: none"> <li>• GeF<sub>4</sub> / H<sub>2</sub></li> <li>• GeF<sub>4</sub> / RG / H<sub>2</sub></li> <li>• GeF<sub>4</sub>/CH<sub>3</sub>F</li> </ul>	-----	Supply chain- super highly enriched gas
C	CO <sub>2</sub> + PH <sub>3</sub>	-----	<ul style="list-style-type: none"> <li>• CO</li> <li>• CO / RG / H<sub>2</sub></li> </ul>	CO/CF <sub>4</sub> + RG/H <sub>2</sub>	Package design and material of construction

RG = rare gas

# Considerations Overview

- Best materials
  - Supply chain reliability
  - Shelf life
  - Cost
  - Packaging and handling options
- Process flexibility
  - Co-flow offers mixture flexibility
  - Mixtures can add stability and shelf life
  - Consumes potentially limited “gas sticks”
- Implanter mode
  - High current, medium current, low energy – high dose
  - Dedicated vs. mixed



# Possible New Implant Species

- New dopants required below 1X node
- Enhanced dosage for electrical or mechanical modification
- No clear gaseous source options yet
- New challenges for delivery, packaging, blending, etc.

Species	Molecule	Phase
Antimony	oxide	Solid
	trifluoride	Solid
Aluminum	trimethyl	Low VP liquid
	trichloride	Solid
Gallium	oxide	Solid
	trimethyl	Low VP liquid

**Expanding beyond gaseous sources**



**Thank you for your time**

**Questions most welcome**

